

## ABSTRACT

Provided are a wafer inspection apparatus, a wafer inspection method and a probe device, by which electrical inspection can be collectively performed as to a great number of electrodes to be inspected, and a good electrically connected state can be surely achieved as to all the electrodes to be inspected under a small load.

The probe device of the invention comprises a circuit board for inspection having a great number of inspection electrodes, a probe card having a circuit board for connection having a great number of terminal electrodes and a contact member, an anisotropically conductive connector arranged between the circuit board for inspection and the circuit board for connection and electrically connecting the respective inspection electrodes to the respective terminal electrodes, and a parallelism adjusting mechanism for adjusting a parallelism of the circuit board for inspection and the circuit board for connection to the wafer. The parallelism adjusting mechanism is equipped with a location-varying mechanism, which relatively displaces the circuit board for inspection or the circuit board for connection in the thickness-wise direction of the anisotropically conductive connector. The wafer inspection apparatus is equipped with the probe device.